

PATENT

Docket No. JCLA20829

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : GUO-CHENG LIAO et al.
Application No. : 11/781,420
Filed : July 23,2007
For : CHIP PACKAGE STRUCTURE

INFORMATION DISCLOSURE STATEMENT
UNDER 35 CFR 1.97(e)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed is a PTO Form 1449 listing (3) references, copies of which are attached. Each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement. Therefore, no fee is due. This Information Disclosure Statement (IDS) is being filed under 37 C.F.R. § 1.97(e). It is requested to place the IDS in the file.

Respectfully submitted,

Dated: December 30, 2009

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